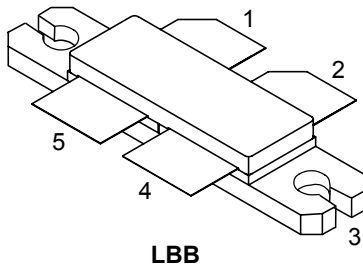


## 120 W 50 V RF power LDMOS transistor from HF to 1.5 GHz



Pin connection	
Pin	Connection
1	Drain A
2	Drain B
3	Source (bottom side)
4	Gate B
5	Gate A

### Features

Order code	Frequency	V <sub>DD</sub>	P <sub>OUT</sub>	Gain	Efficiency
RF5L15120CB4	1000 MHz	50 V	120 W	20 dB	60%

- High efficiency and linear gain operations
- Integrated ESD protection
- Large positive and negative gate/source voltage range
- Excellent thermal stability, low HCI drift
- In compliance with the european directive 2002/95/EC

### Applications

- Broadband commercial communications
- TV broadcast
- Avionics
- Industrial

### Description

The RF5L15120CB4 is a 120 W LDMOS FET, designed for broadband commercial communications, TV Broadcast, Avionics and industrial applications with frequencies from HF to 1.5 GHz. It can be used in class AB/B and class C for all typical modulation formats.



Product status link
<a href="#">RF5L15120CB4</a>

Product summary	
Order code	RF5L15120CB4
Marking	RF5L15120CB4
Package	LBB
Packing	Tape and reel 13"
Base/bulk quantity	100/100

# 1 Electrical data

## 1.1 Absolute ratings

**Table 1. Absolute maximum ratings ( $T_{CASE} = 25\text{ °C}$ )**

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-source voltage	95	V
$V_{GS}$	Gate-source voltage	-8/+10	V
$V_{DD}$	Maximum operating voltage	55	V
$T_J$	Maximum junction temperature	+200	°C
$T_{STG}$	Storage temperature range	-65 to +150	°C

## 1.2 Thermal data

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Junction-case thermal resistance	0.7	°C/W

*Note:*  $T_{CASE} = +85\text{ °C}$ ,  $T_J = +200\text{ °C}$ , DC test.

## 1.3 ESD protection characteristics

**Table 3. ESD protection**

Symbol	Test methodology	Class
HBM	Human body model (per JESD22-A114)	2

## 2 Electrical characteristics

### 2.1 Static

**Table 4. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_{DS} = 0.5\text{ mA}$	95			V
$I_{DSS}$	Zero gate voltage drain leakage current	$V_{GS} = 0\text{ V}, V_{DS} = 90\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}, V_{DS} = 50\text{ V}$				
$I_{GSS}$	Gate-source leakage current	$V_{GS} = 10\text{ V}, V_{DS} = 0\text{ V}$			100	nA
		$V_{GS} = -8\text{ V}, V_{DS} = 0\text{ V}$				
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = 50\text{ V}, I_{DS} = 600\text{ }\mu\text{A}$	2		2.8	V
$V_{GS(Q)}$	Gate quiescent voltage	$V_{DS} = 50\text{ V}, I_{DS} = 400\text{ mA}$	2		6	V
$V_{DS(on)}$	Static drain-source on-voltage	$V_{GS} = 10\text{ V}, I_{DS} = 2\text{ A}$			1.2	V
$I_{DS(on)}$	Static drain-source on-current	$V_{GS} = 10\text{ V}, V_{DS} = 100\text{ mV}$			2.5	A
$R_{DS(on)}$	Drain-source on-state resistance	$V_{GS} = 10\text{ V}, V_{DS} = 100\text{ mV}$			1	$\Omega$
$C_{ISS}$	Common source input capacitance	$V_{GS} = 0\text{ V}, V_{DD} = 50\text{ V},$ $f = 1\text{ MHz}$		56		pF
$C_{RSS}$	Common source feedback capacitance			0.6		pF
$C_{OSS}$	Common source output capacitance			23		pF

### 2.2 Dynamic

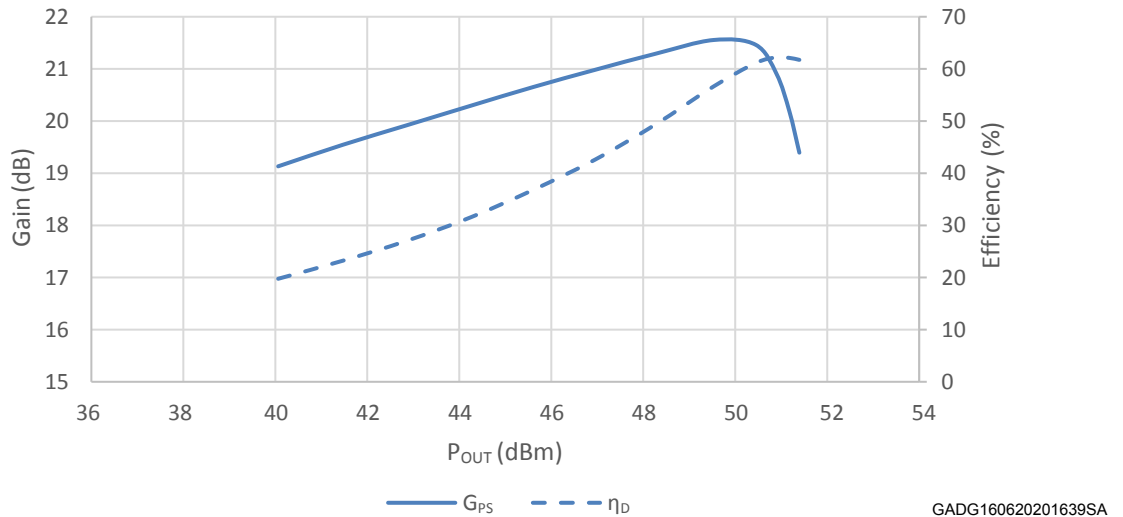
**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
f	Frequency				1500	MHz
$P_{OUT}$	Output power	f = 1000 MHz, at 1dB compression point, pulsed CW		120		W
$G_{PS}$	Power gain			20		dB
$\eta_D$	Drain efficiency			60		%
VSWR	Load mismatch	At 120 W pulsed CW output power, all phase angles			10:1	

Note:  $V_{DD} = 50\text{ V}, I_{DQ} = 100\text{ mA},$  pulse width = 100  $\mu\text{s},$  duty cycle = 10%.

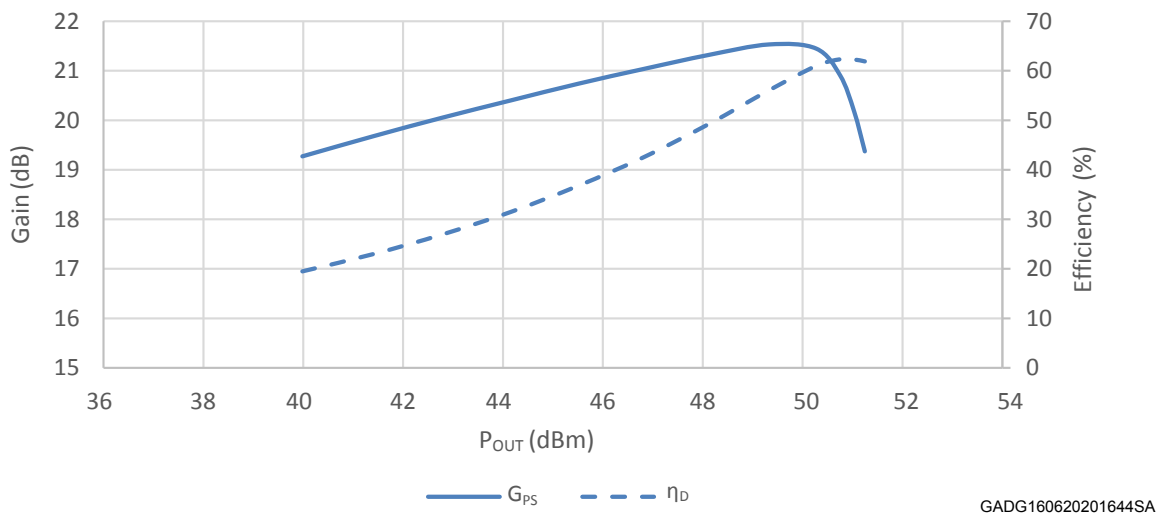
### 3 Typical performances

**Figure 1. Power gain and drain efficiency versus output power (f = 1000 MHz, pulsed CW)**



Note:  $V_{DD} = 50\text{ V}$ ,  $I_{DQ} = 100\text{ mA}$ , pulsed CW; pulse width = 100  $\mu\text{s}$ , duty cycle = 10%.

**Figure 2. Power gain and drain efficiency versus output power (f = 1000 MHz, CW)**

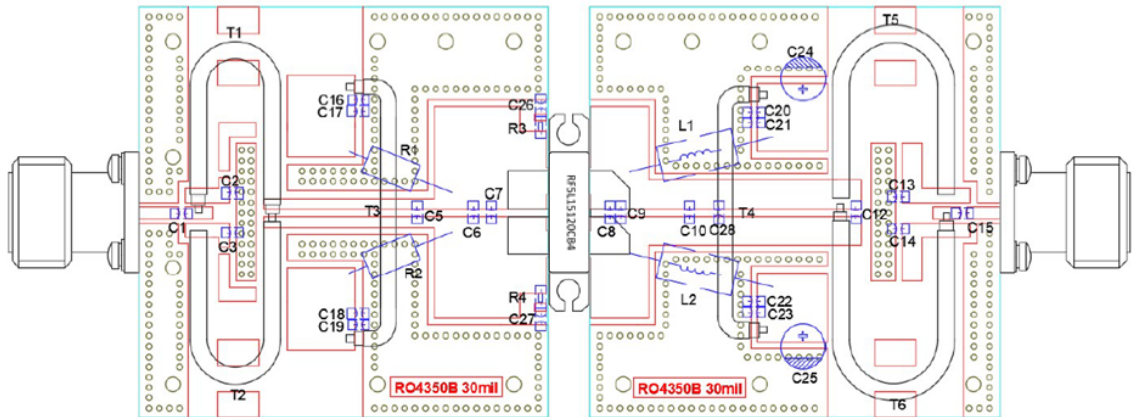


Note:  $V_{DD} = 50\text{ V}$ ,  $I_{DQ} = 100\text{ mA}$ .

## 4 Test circuit

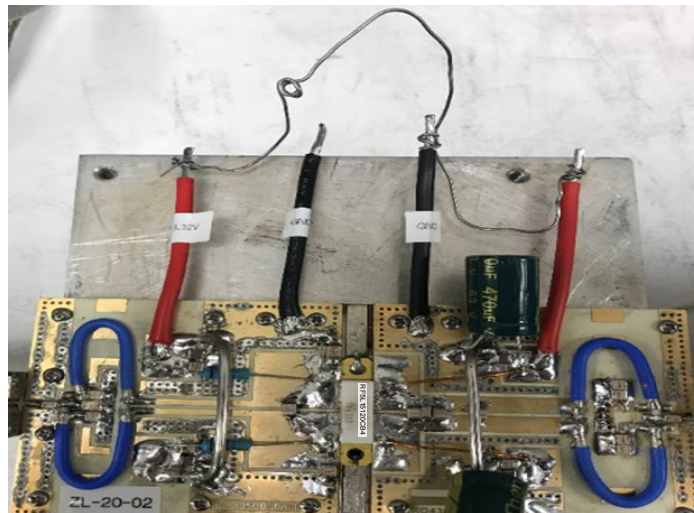
### 4.1 Test circuit layout

Figure 3. Test circuit layout (f = 1000 MHz)



GADG170620201720SA

Figure 4. Test circuit photo (f = 1000 MHz)



GADG160620201621SA

**Table 6. Components list**

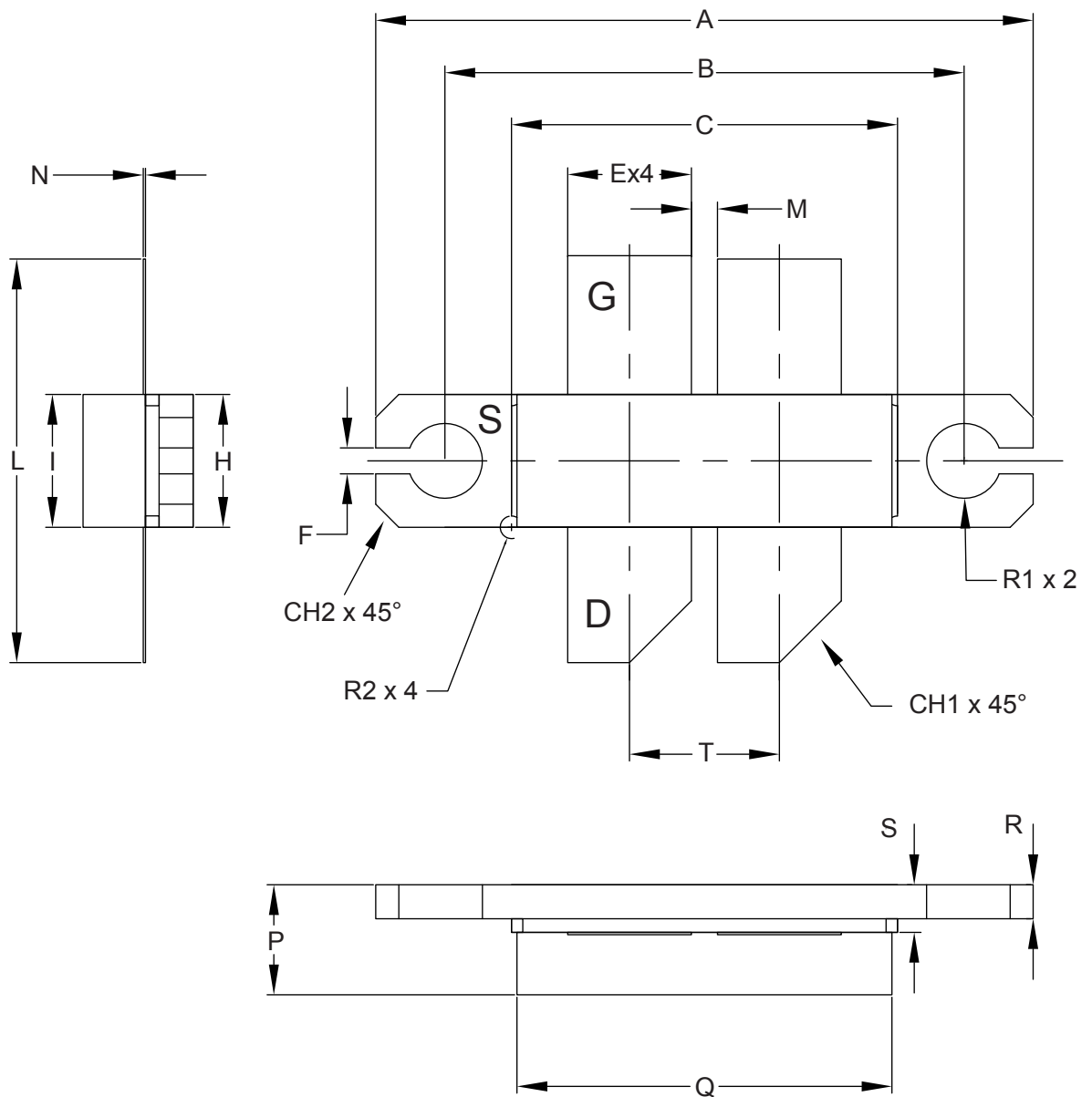
Component	Description	Suggested manufacturer
C1, C2, C3, C13, C14, C15, C17, C18, C21, C22, C26, C27	120 pF	ATC800B
C5	6.8 pF	ATC800B
C6	5.6 pF	ATC800B
C7	10 pF	ATC800B
C12	3.3 pF	ATC800B
C8, C9, C10, C28	8.2 pF	ATC800B
C16, C19, C20, C23	Ceramic multilayer capacitor, 10 $\mu$ F, 100 V	10 $\mu$ F/100 V
R1, R2	Metal film resistor, 200 $\Omega$	
R4, R5	Chip resistor, 13 $\Omega$ , 1206	
L1, L2	Copper wire, cross section diameter 0.8 mm	
C24, C25	Electrolytic capacitor, 470 $\mu$ F, 63 V	
PCB	0.762 mm [0.030"] thick, $\epsilon_r= 3.48$ , Rogers RO4350B, 1 oz. copper	

## 5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 5.1 LBB package information

Figure 5. LBB package outline



DM00666717\_2

**Table 7. LBB mechanical data**

Symbol	Millimeters		
	Min.	Typ.	Max.
A	28.82	28.95	29.08
B	22.73	22.86	22.99
C	16.87	17.00	17.13
E	5.32	5.45	5.58
F	1.01	1.14	1.27
H	5.72	5.85	5.98
I	5.72	5.85	5.98
L	17.65	17.78	17.91
M	1.02	1.15	1.28
N		0.10	
P	4.72	4.85	4.98
Q	16.38	16.51	16.64
R	1.37	1.50	1.63
S	1.97	2.10	2.23
T		6.60	
CH1		2.72	
CH2		1.02	
R1		1.65	
R2		0.50	



## Revision history

**Table 8. Document revision history**

Date	Version	Changes
16-Jun-2020	1	First release

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